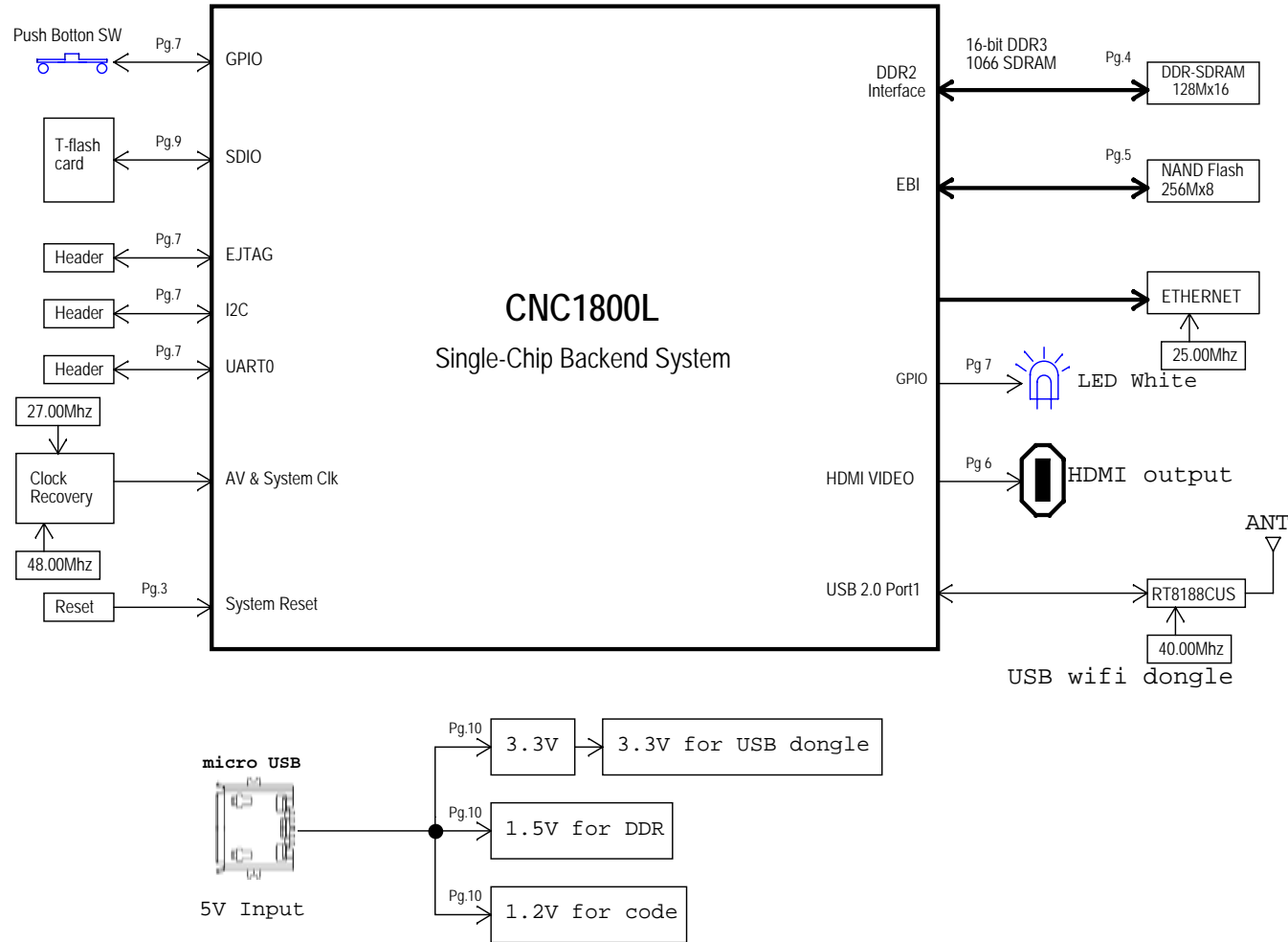


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**S C H E M A T I C Version 1.0**

PAGE	DESCRIPTION
1	Title & Contents
2	Notes & Block Diagram
3	System Config&Ethetnet
4	DDR3 Interface
5	NAND Flash
6	HDMI & USB Interface
7	Peripheral:I2c,JTAG,UART,LED,PBSW
8	Decoupling&AV out
9	Power
10	WiFi
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13	
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15	

## 10TT Block Diagram



### Revision History:

Rev	Description	Date	Approved
1	Preliminary Release	2012/09/19	

### Layout Notes:

1. Discrete (especially resistors) should be placed close to Large components which are on the same schematic page

NOTES, UNLESS OTHERWISE SPECIFIED:

1. RESISTANCE VALUES IN OHMS.
2. CAPACITANCE VALUES IN MICROFARADS.
3. REFERENCE DESIGNATORS USED.
4. ALL 0.1 uF CAPACITORS ARE DECOUPLING CAPS UNLESS OTHERWISE NOTED. THEY ARE SHOWN ON THE PAGE WITH THE INTEGRATED CIRCUITS THEY SHOULD BE PLACED NEAR.
5. BOARD PROPERTIES:
  - A. FR-4 RoHS COMPLIANT MATERIAL PER IPC-4101/129 OR BETTER
  - B. ALL SIGNAL LAYERS - 0.5 OZ CU
  - C. PLANE LAYERS - 0.5 OZ CU
  - D. IMPEDENCE CONTROL:
    - 50 OHMS +/- 10% SINGLE ENDED TRACES
    - 60 OHMS +/- 10% SINGLE ENDED TRACES
    - 90 OHMS +/- 10% SINGLE ENDED TRACES
    - 100 OHMS +/- 10% DIFFERENTIAL TRACES
  - E. LAYER STACKUP:

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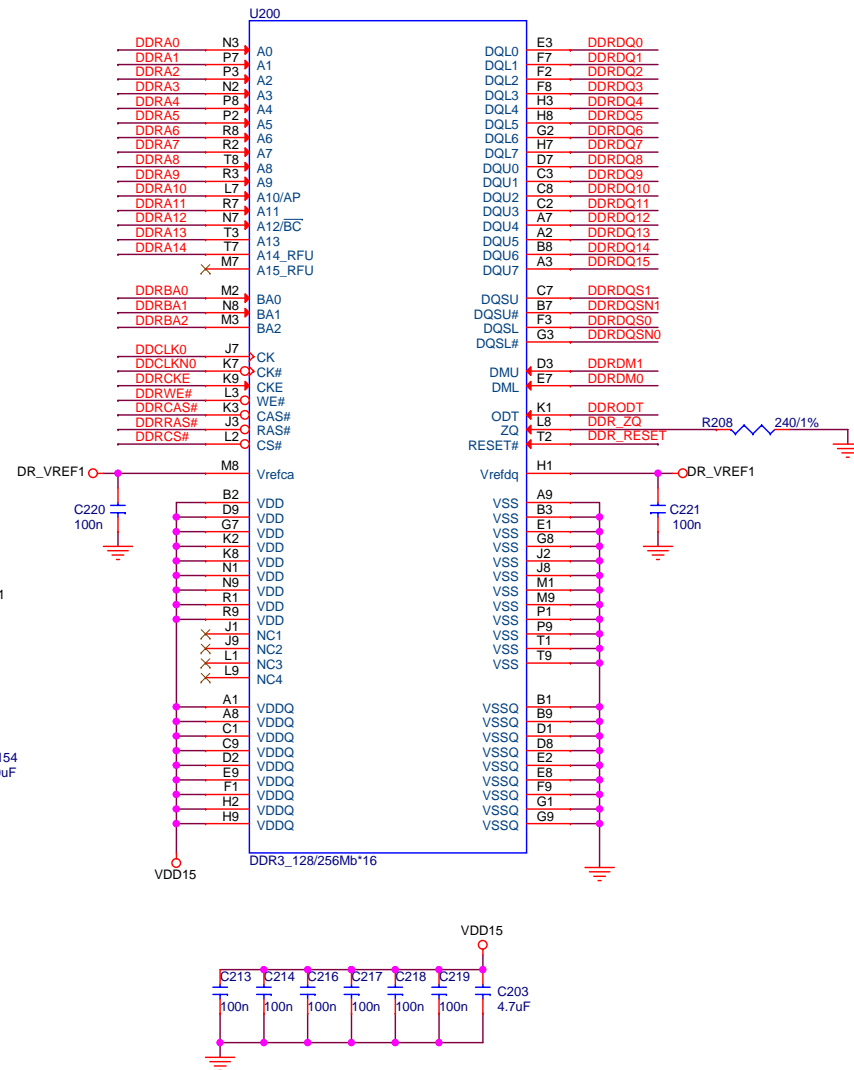
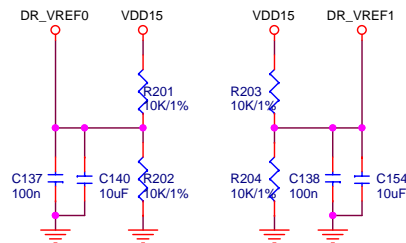
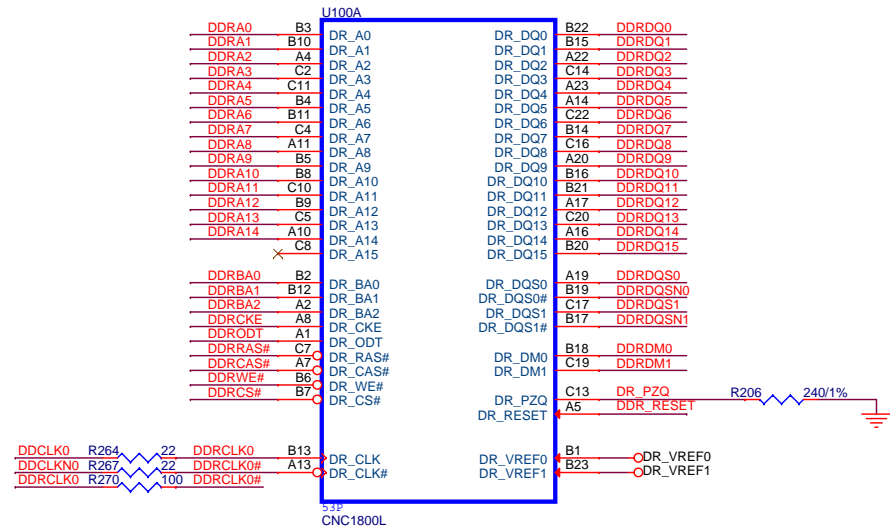
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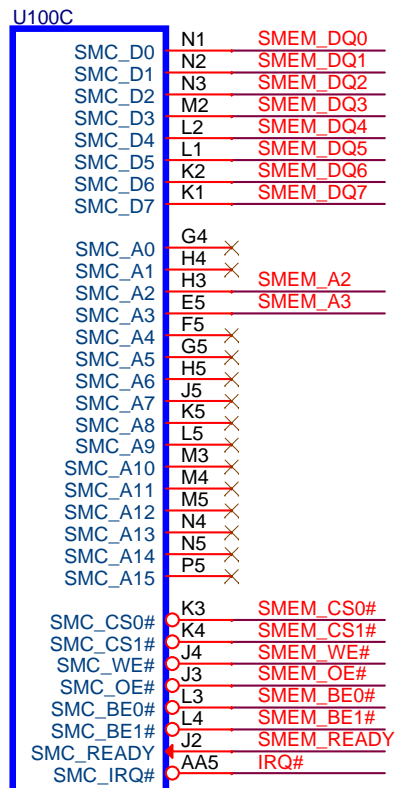


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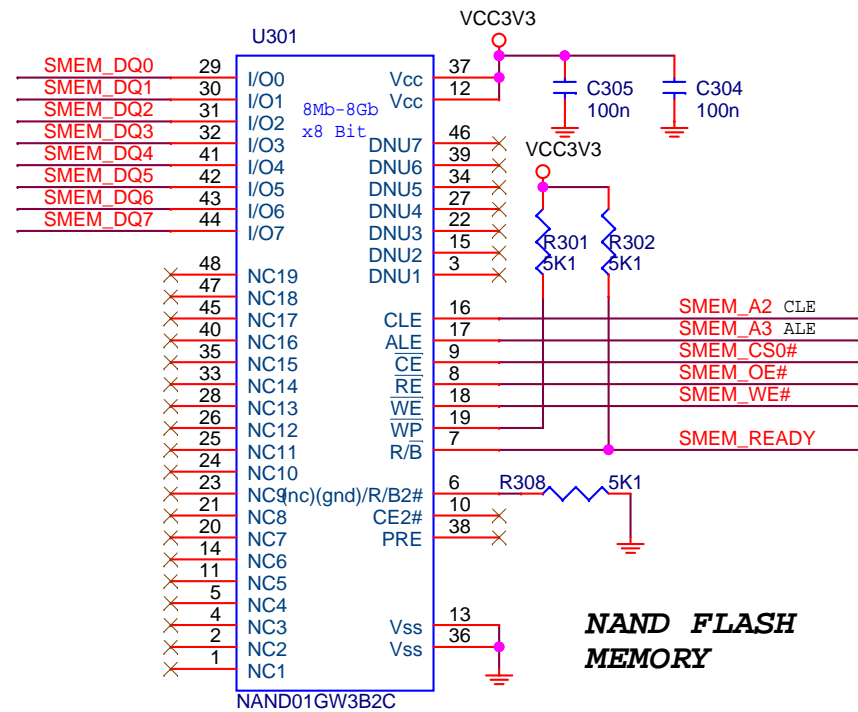
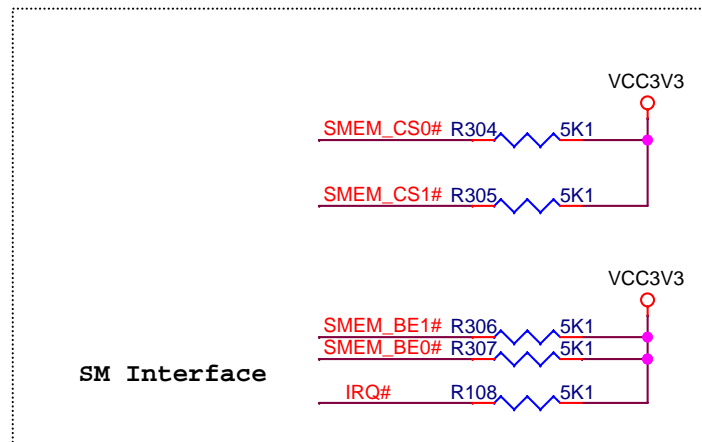
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32P  
CNC1800L



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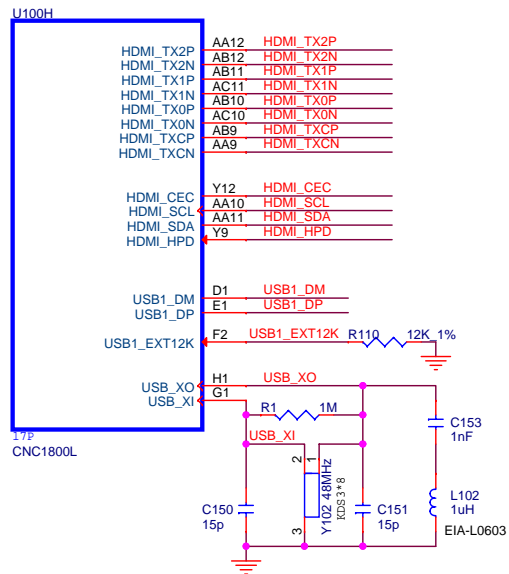
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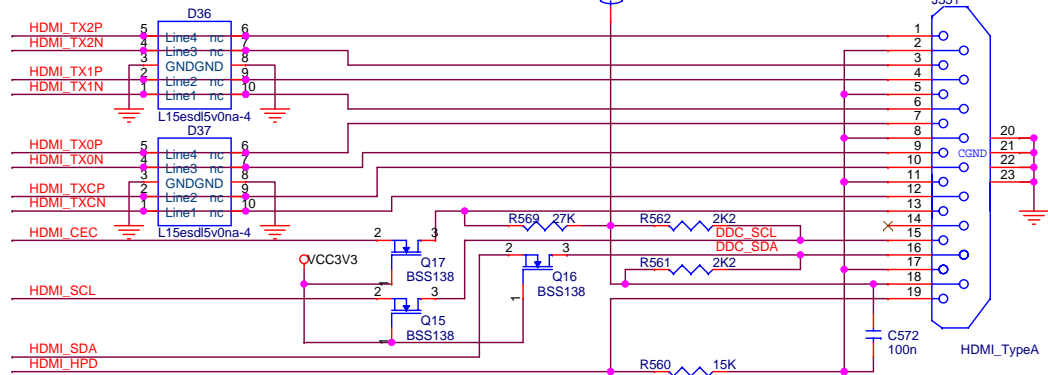
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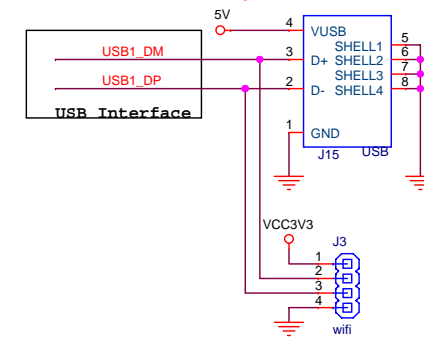
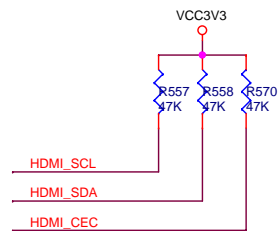
**HDMI - Layout Guidelines:**

- Differential pairs should be routed on TOP or BOTTOM layers only.
- Trace impedance: 100 ohm differential impedance to the ground plane.
- 5.5 mils trace width with 5 mil air gap on P/N pair.
- Match trace length of differential pairs, 20 mils max within a pair, and 100 mils max between pairs.
- Adjacent TX/RX differential pairs should be separated by more than 50 mils to each other.



**USB - Layout Guidelines:**

- Dp and Dn differential pairs should be routed on TOP or BOTTOM layer only.
- Match trace length of Dp and Dn differential pairs, 20 mils max within a pair, and 100 mils max between pairs.
- The length for the differential pairs should be less than 5 inches.
- Do not place more than 2 vias per trace, prefer zero.
- Never split the ground plane under differential pairs when routing.
- Route differential pairs above the GND plane.
- Differential impedance is 90 Ohms (7.5 mils trace width with 5.5 mils air gap) for USB
- Adjacent differential pairs should be separated by at least 3 times the trace width. (e.g. 5 mils trace, leave >15 mils between adjacent differential pairs)
- Stitch GND vias around each differential pair, but NOT between a given pair.
- Placement of USB needs to be in opposite side of the board from the HDMI circuitry

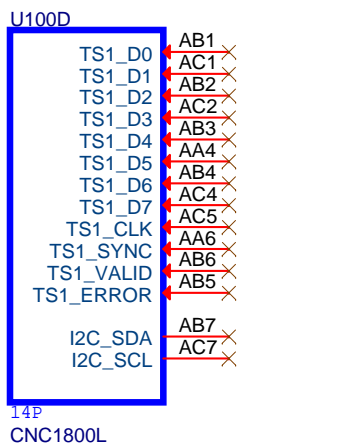
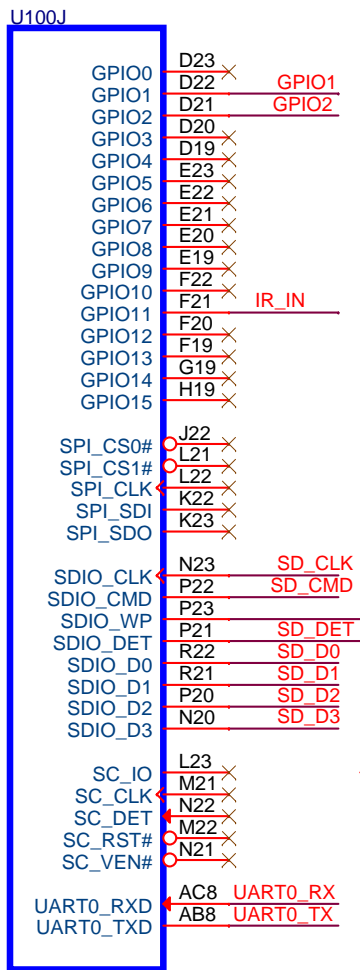


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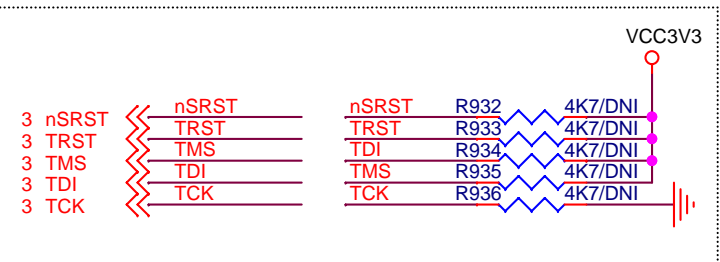
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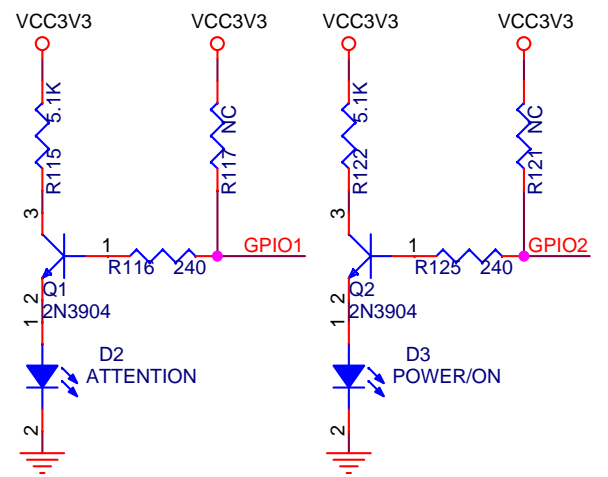
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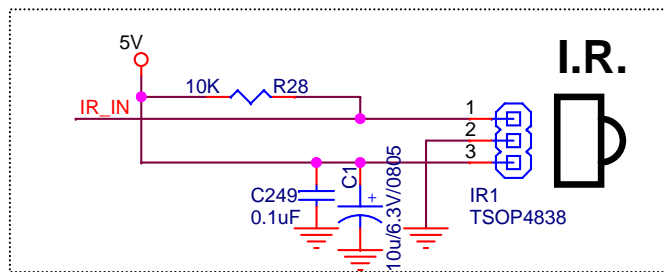
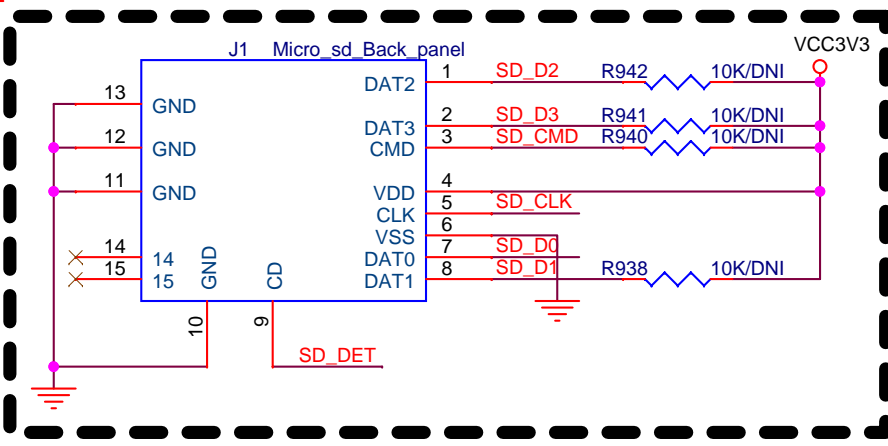
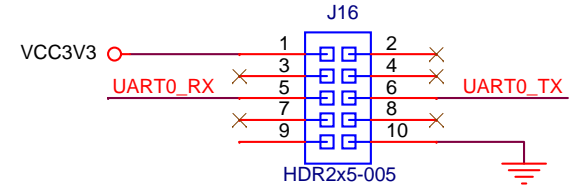
## UART0 PORT




## LED Indicate state



## RS232 Debug Use



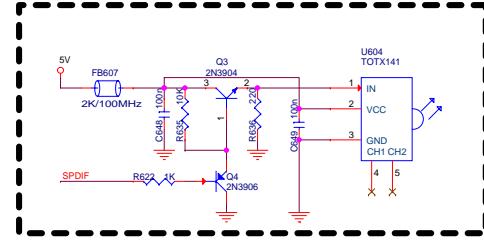
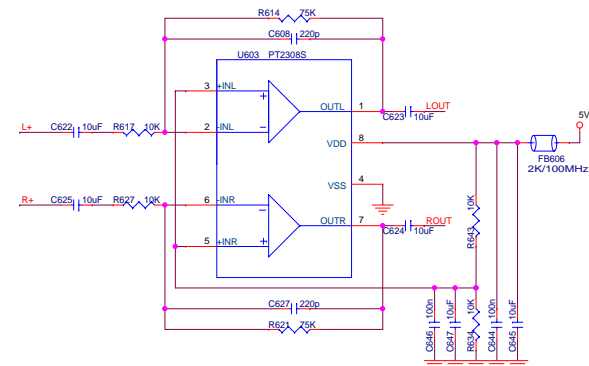
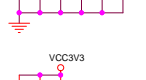
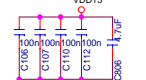
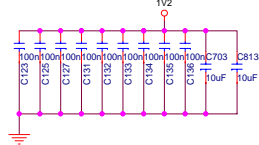
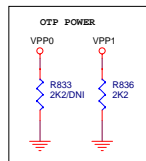
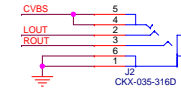
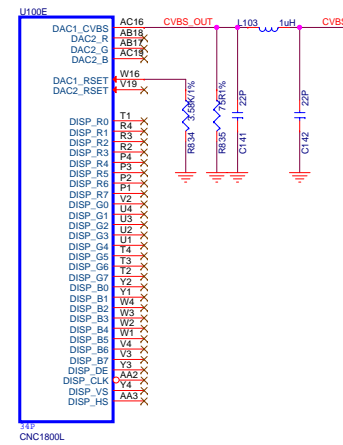
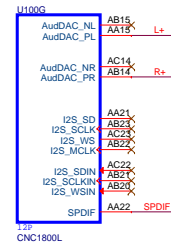
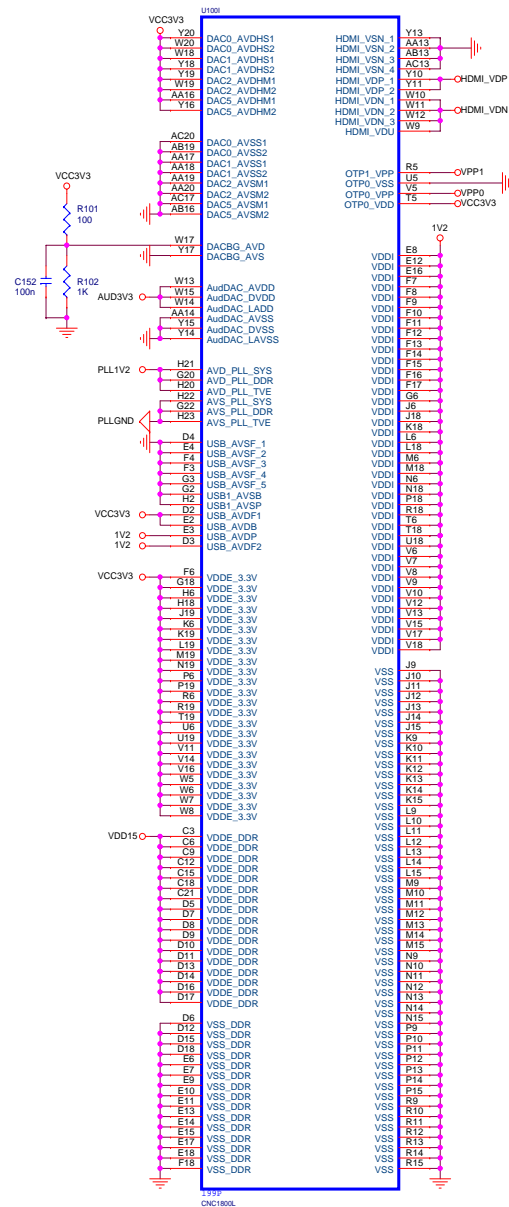
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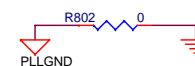
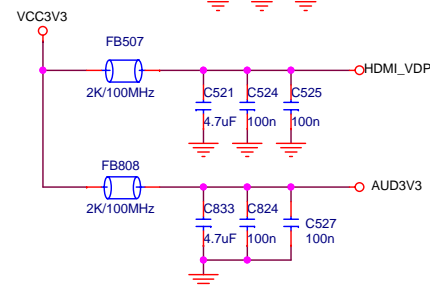
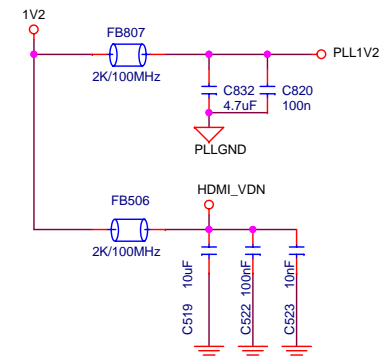
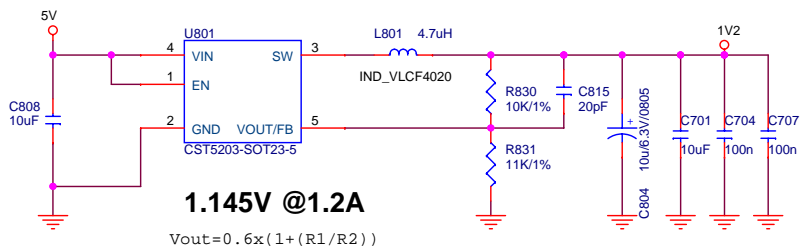
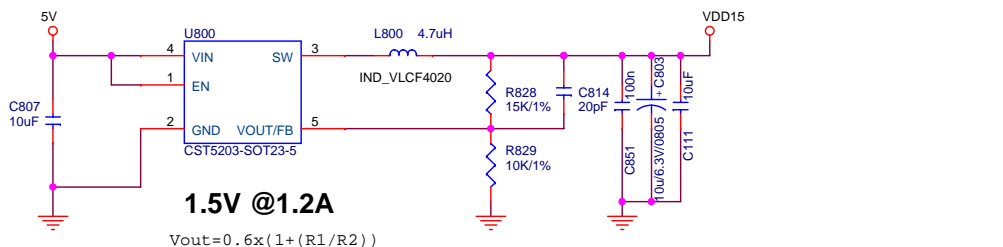
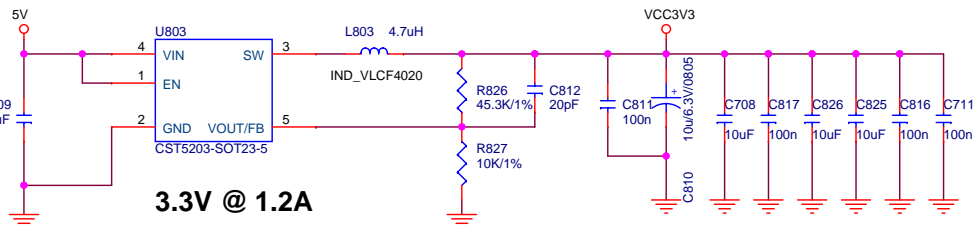
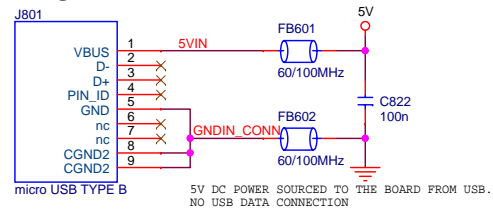
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